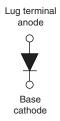


HEXFRED® Ultrafast Soft Recovery Diode, 275 A





PRODUCT SUMMARY					
I _F (maximum)	275 A				
V _R	400 V				
I _{F(DC)} at T _C	138 A at 100 °C				
Package	HALF-PAK (D-67)				
Circuit	Single diode				

FEATURES

- Very low Q_{rr} and t_{rr}
- · Designed and qualified for industrial level
- UL approved file E222165





- Reduced RFI and EMI
- · Reduced snubbing

DESCRIPTION

BENEFITS

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dl/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Cathode to anode voltage	V_R		400	V	
Continuous forward current	I _F	T _C = 25 °C	275		
		T _C = 100 °C	138	Α	
Single pulse forward current	I _{FSM}	Limited by junction temperature	900		
Non-repetitive avalanche energy	E _{AS}	$L = 100 \mu H$, duty cycle limited by maximum T_J	1.4	mJ	
Maximum power dissipation	P _D	$T_{C} = 25 ^{\circ}C$ 463		W	
		T _C = 100 °C	185] vv	
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C	

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	I _R = 100 μA		400	ı	ı	
Maximum forward voltage		I _F = 135 A		-	1.06	1.65	V
	V_{FM}	I _F = 270 A		1.2	2.0		
		I _F = 135 A, T _J = 125 °C		-	0.96	1.58	
Maximum reverse leakage current	I _{RM}	T _J = 125 °C, V _R = 400 V	See fig. 2	-	-	3	mA
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	280	380	pF
Series inductance	L _S	From top of terminal hole to mounting plane		ı	6.0	- 1	nH

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5	t _{rr}	T _J = 25 °C	$I_F = 135 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	77	120	- ns
		T _J = 125 °C		-	280	440	
Peak recovery current See fig. 6	I _{RRM}	T _J = 25 °C		-	7.5	14	Α
		T _J = 125 °C		-	15	30	
Reverse recovery charge See fig. 7	Q _{rr}	T _J = 25 °C		-	150	780	nC
		T _J = 125 °C		-	2800	6300	
Peak rate of recovery current See fig. 8	-11 /-14	T _J = 25 °C		-	350	-	- A/μs
	dI _{(rec)M} /dt	T _J = 125 °C		-	300	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL TEST CONDITIONS		VALUES	UNITS	
Maximum junction and storage temperature range		T _J , T _{Stg}		-55 to +150	°C	
Maximum thermal resistance, junction to case		R _{thJC}	DC operation See fig. 4	0.27	°C/W	
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, flat, smooth and greased	0.05		
Approximate weight				30	g	
				1.06	OZ.	
Marintina tararra	minimum			3 (26.5)		
Mounting torque	maximum			4 (35.4)	N⋅m	
Terminal torque	minimum			3.4 (30)	(lbf·in)	
	maximum			5 (44.2)		
Case style			HALF-PAK module			

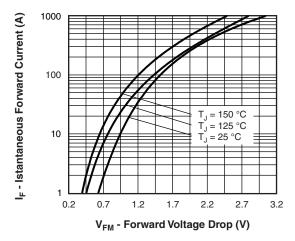


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

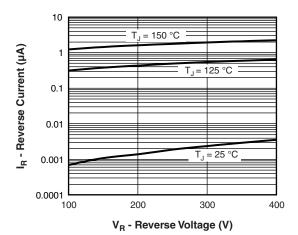


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

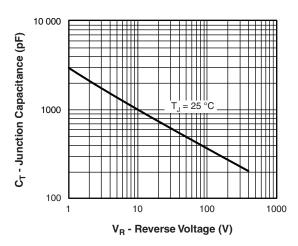


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

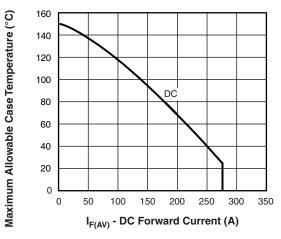


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current

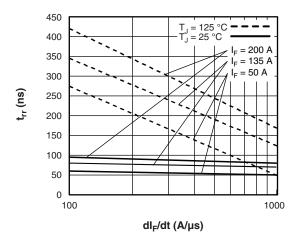


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt

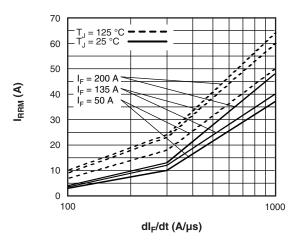


Fig. 6 - Typical Recovery Current vs. dI_F/dt

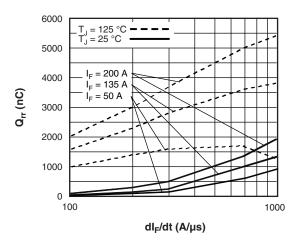


Fig. 7 - Typical Stored Charge vs. dl_F/dt

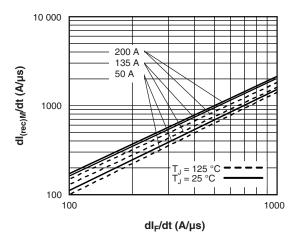


Fig. 8 - Typical dl_{(rec)M}/dt vs. dl_F/dt

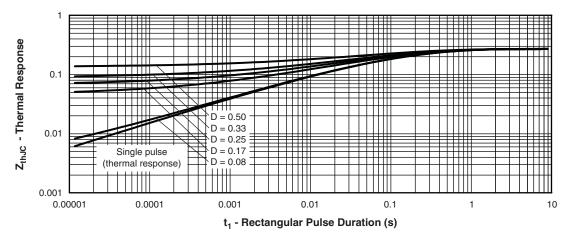


Fig. 9 - Maximum Thermal Impedance Z_{thJC} Characteristics

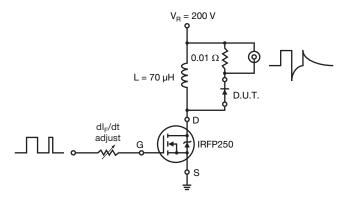
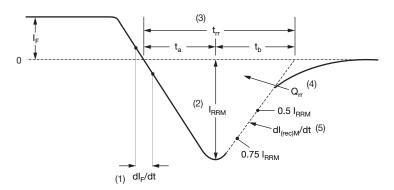


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) dI_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) dl_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 11 - Reverse Recovery Waveform and Definitions



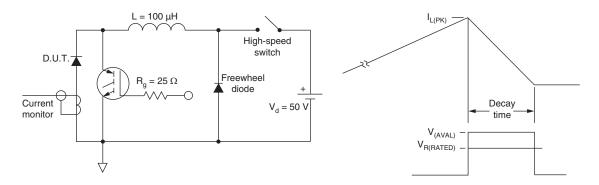
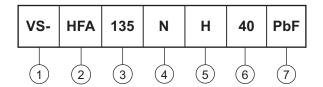


Fig. 12 - Avalanche Test Circuit and Waveforms

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

- HEXFRED® family

Average current rating

4 - N = Not isolated

5 - H = HALF-PAK

6 - Voltage rating (400 V)

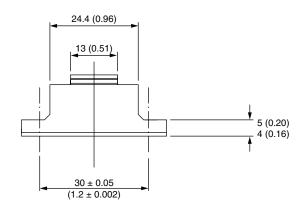
7 - Lead (Pb)-free

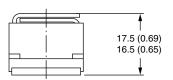
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95020			

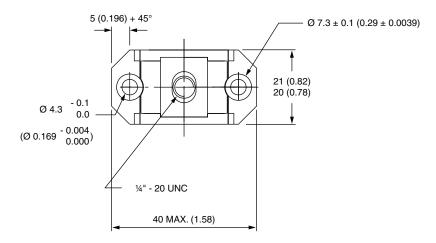


D-67 HALF-PAK

DIMENSIONS in millimeters (inches)









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